



浙江世菱半导体有限公司  
ZHEJIANG SHILING SEMICONDUCTOR CO.,LTD.

## 产品规格书

Specification of products

产品名称：三相全控桥

产品型号：MDST200A-H4

浙江世菱半导体有限公司  
ZHEJIANG SHILING SEMICONDUCTOR CO., LTD.

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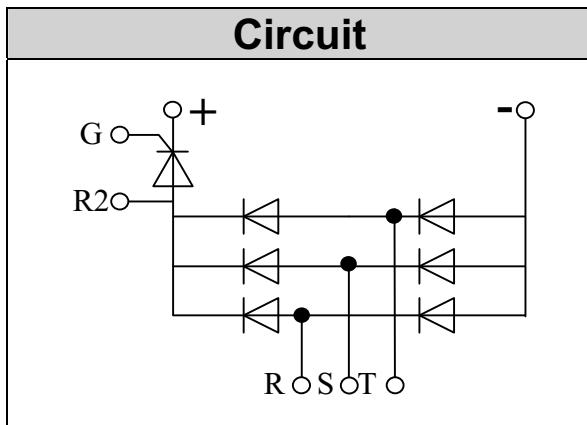
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## Three Phase Bridge + Thyristor

**V<sub>RRM</sub> / V<sub>DRM</sub>** 800 to 1800V

**I<sub>FAV</sub> / I<sub>TAV</sub>** 200A

### Features

- Blocking voltage: 800 to 1800V
- Three Phase Bridge and a Thyristor
- Low Forward Voltage

### Applications

- Inverter for AC or DC motor control
- Current stabilized power supply
- Switching power supply

### Module Type

TYPE	V <sub>RRM</sub> / V <sub>DRM</sub>	V <sub>RS</sub>
MDST200A800V	800V	900V
MDST200A1200V	1200V	1300V
MDST200A1600V	1600V	1700V
MDST200A1800V	1800V	1900V

### ◆Diode

### Maximum Ratings

Symbol	Item	Conditions	Values	Units
I <sub>D</sub>	Output Current(D.C.)	T <sub>c</sub> =96 °C Three phase full wave	200	A
I <sub>FSM</sub>	Surge forward current	t=10mS T <sub>vj</sub> =45°C	1900	A
i <sup>2</sup> t	Circuit Fusing Consideration		18050	A <sup>2</sup> s
V <sub>Isol</sub>	Isolation Breakdown Voltage(R.M.S)	a.c.50HZ;r.m.s.;1min	3000	V
T <sub>vj</sub>	Operating Junction Temperature		-40 to +150	°C
T <sub>stg</sub>	Storage Temperature		-40 to +125	°C
M <sub>t</sub>	Mounting Torque	To terminals(M4)	2±5%	Nm
M <sub>t</sub>		To terminals(M6)	5±15%	Nm
M <sub>s</sub>		To heatsink(M6)	5±15%	Nm
Weight		Module (Approximately)	320	g

### Thermal Characteristics

Symbol	Item	Conditions	Values	Units
R <sub>th(j-c)</sub>	Thermal Impedance, max.	Junction to Case(TOTAL)	0.12	°C/W
R <sub>th(c-s)</sub>	Thermal Impedance, max.	Case to Heat sink	0.06	°C/W

### Electrical Characteristics

Symbol	Item	Conditions	Values	Units
V <sub>FM</sub>	Forward Voltage Drop, max.	T=25°C IF =200A	1.30	V
I <sub>IRRM</sub>	Repetitive Peak Reverse Current, max.	T <sub>vj</sub> =25°C VRD=V <sub>RRM</sub> T <sub>vj</sub> =150°C VRD=V <sub>RRM</sub>	≤2 ≤10	mA mA

◆Thyristor  
Maximum Ratings

Symbol	Item	Conditions	Values	Units
I <sub>TAV</sub>	Average On-State Current	T <sub>C</sub> =93 °C, Single Phase half wave 180° conduction	200	A
I <sub>TSM</sub>	Surge On-State Current	T <sub>VJ</sub> =45°C t=10ms (50Hz), sine VR=0	1900	A
i <sup>2</sup> t	Circuit Fusing Consideration		18050	A <sup>2</sup> s
Visol	Isolation Breakdown Voltage(R.M.S)	a.c.50HZ;r.m.s.;1 min	3000	V
T <sub>vj</sub>	Operating Junction Temperature		-40 to +125	°C
T <sub>stg</sub>	Storage Temperature		-40 to +125	°C
M <sub>t</sub>	Mounting Torque	To terminals(M4)	25%	Nm
M <sub>t</sub>		To terminals(M6)	5±5%	Nm
M <sub>s</sub>		To heatsink(M6)	5±5%	Nm
di/dt	Critical Rate of Rise of On-State Current	T <sub>VJ</sub> =T <sub>VJM</sub> , V <sub>D</sub> =1/2V <sub>DRM</sub> , I <sub>G</sub> =100mA d <sub>IG</sub> /d <sub>t</sub> =0.1A/μs	200	A/μs
dv/dt	Critical Rate of Rise of Off-State Voltage, min.	T <sub>J</sub> =T <sub>VJM</sub> , V <sub>D</sub> =2/3V <sub>DRM</sub> , linear voltage rise	500	V/μs

### Electrical and Thermal Characteristics

Symbol	Item	Conditions	Values			Units
			Min.	Typ.	Max.	
V <sub>TM</sub>	Peak On-State Voltage, max.	T=25°C I <sub>T</sub> =200A		1.35	V	
I <sub>RRM</sub> /I <sub>DRM</sub>	Repetitive Peak Reverse Current, max. / Repetitive Peak Off-State Current, max.	T <sub>VJ</sub> =T <sub>VJM</sub> , V <sub>R</sub> =V <sub>RRM</sub> , V <sub>D</sub> =V <sub>DRM</sub>		100	mA	
V <sub>GT</sub>	Gate Trigger Voltage, max.	T <sub>VJ</sub> =25°C , V <sub>D</sub> =6V		3	V	
I <sub>GT</sub>	Gate Trigger Current, max.	T <sub>VJ</sub> =25°C , V <sub>D</sub> =6V		150	mA	
R <sub>th(j-c)</sub>	Thermal Impedance, max.	Junction to Case			0.14	°C/W
R <sub>th(c-s)</sub>	Thermal Impedance, max.	Case to Heatsink			0.06	°C/W

## Performance Curves

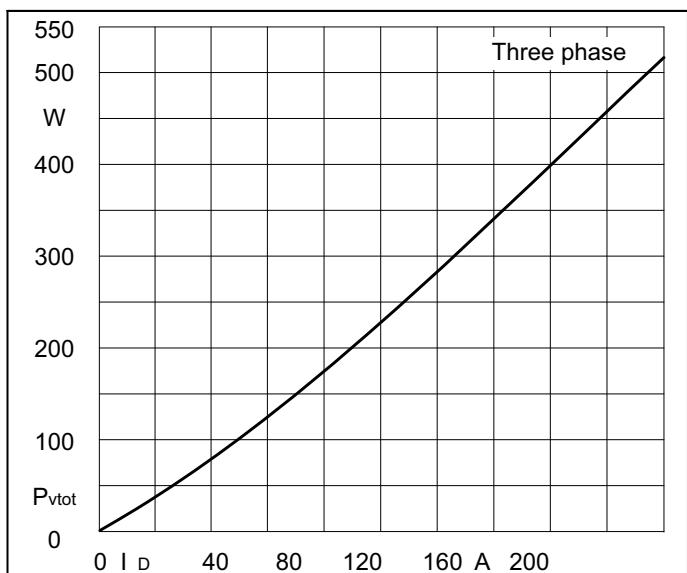


Fig1. Power dissipation

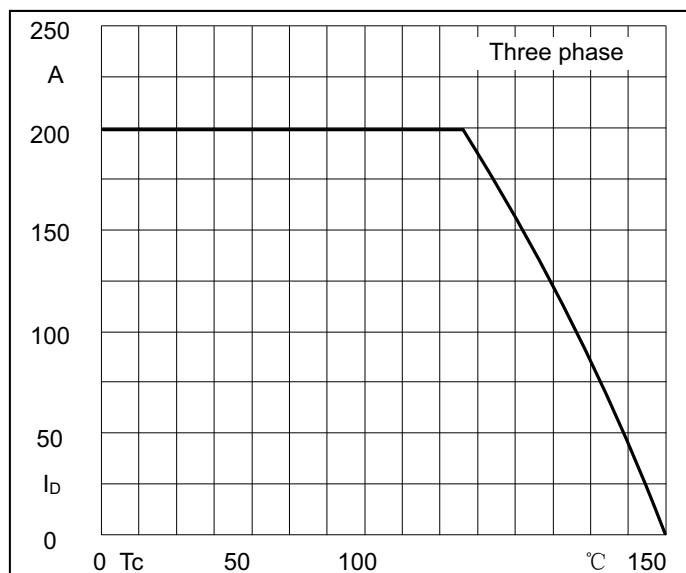


Fig2. Forward Current Derating Curve

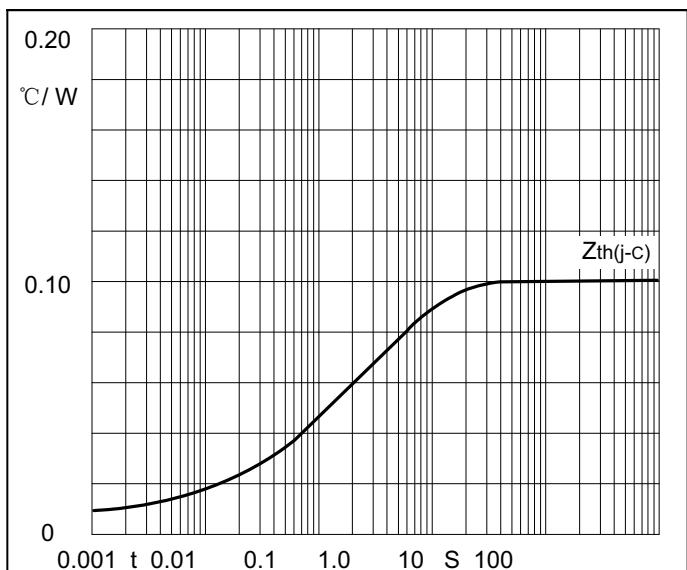


Fig3. Transient thermal impedance

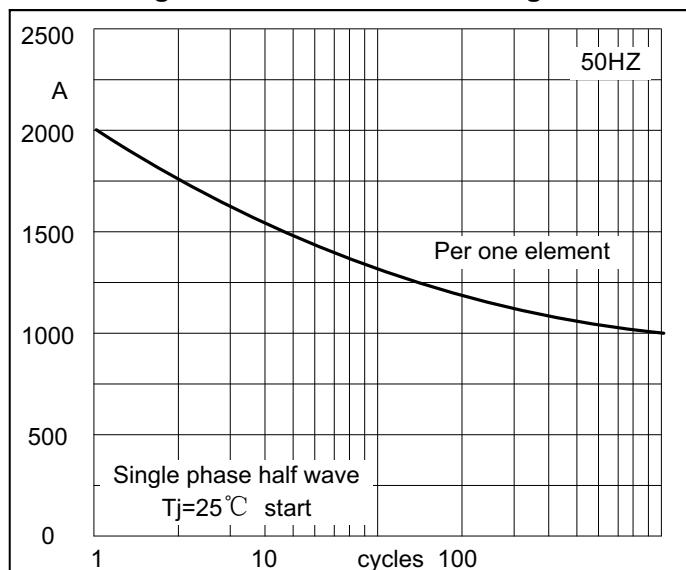


Fig4. Max Non-Repetitive Forward Surge Current

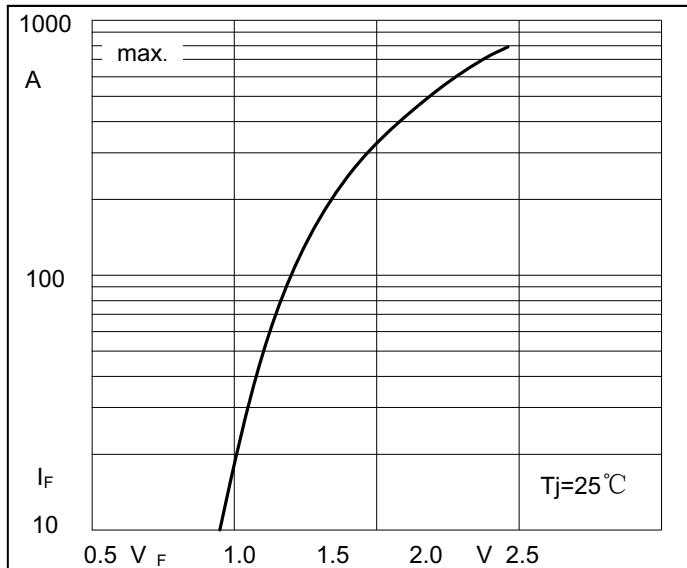


Fig5. Forward Characteristics

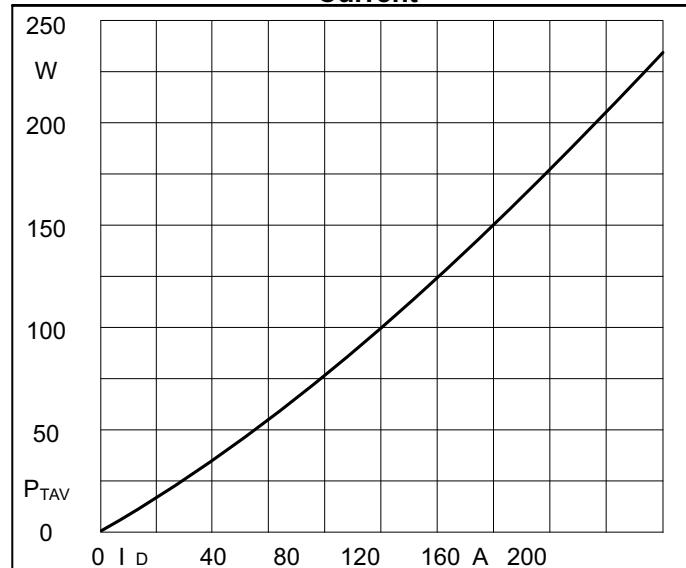


Fig6. SCR Power dissipation

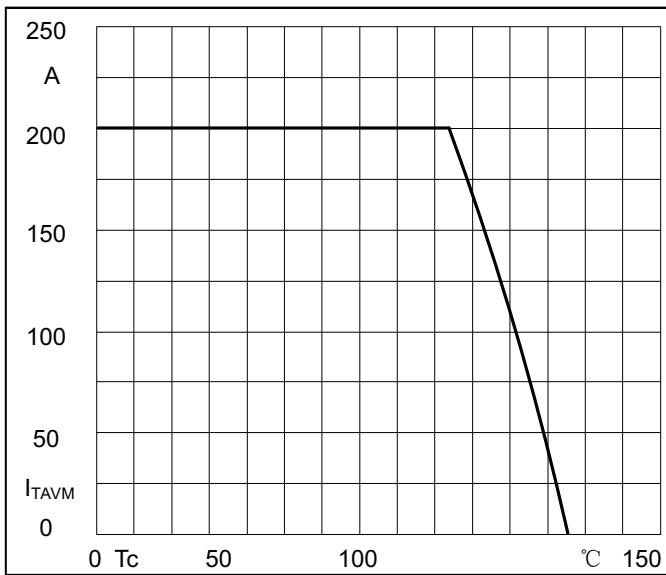


Fig7. SCR Forward Current Derating Curve

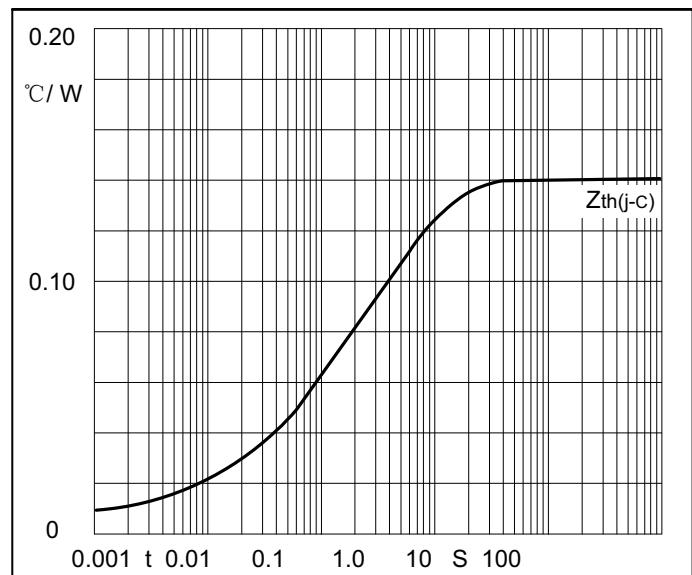


Fig8. SCR Transient thermal impedance

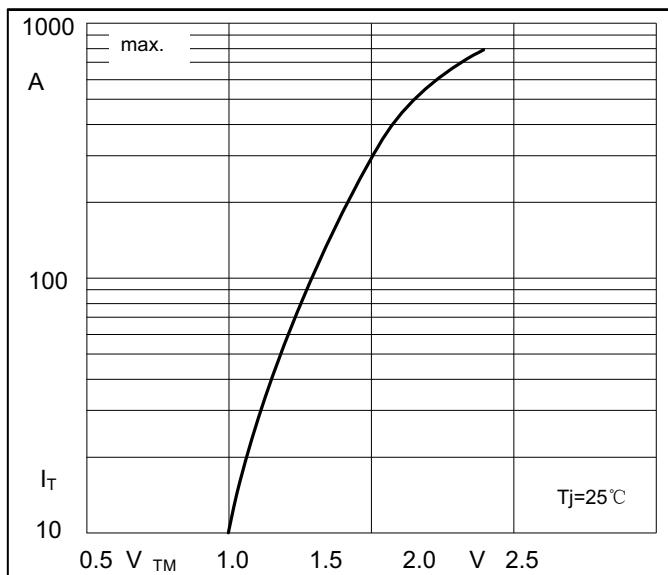


Fig9. SCR Forward Characteristics

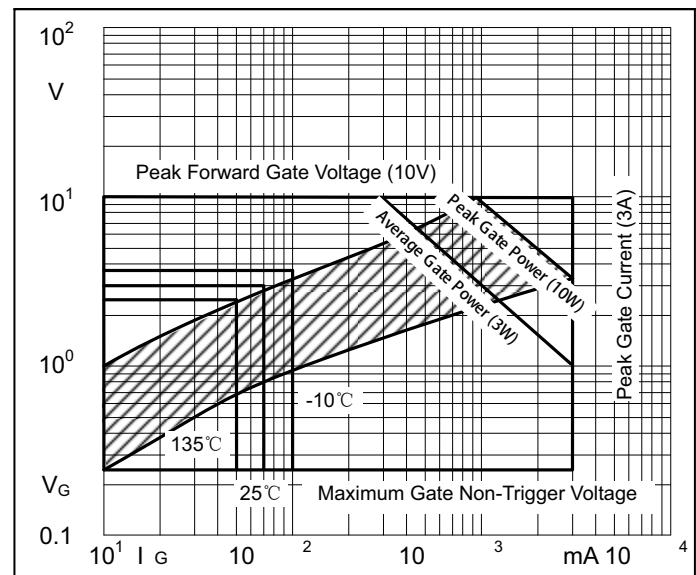
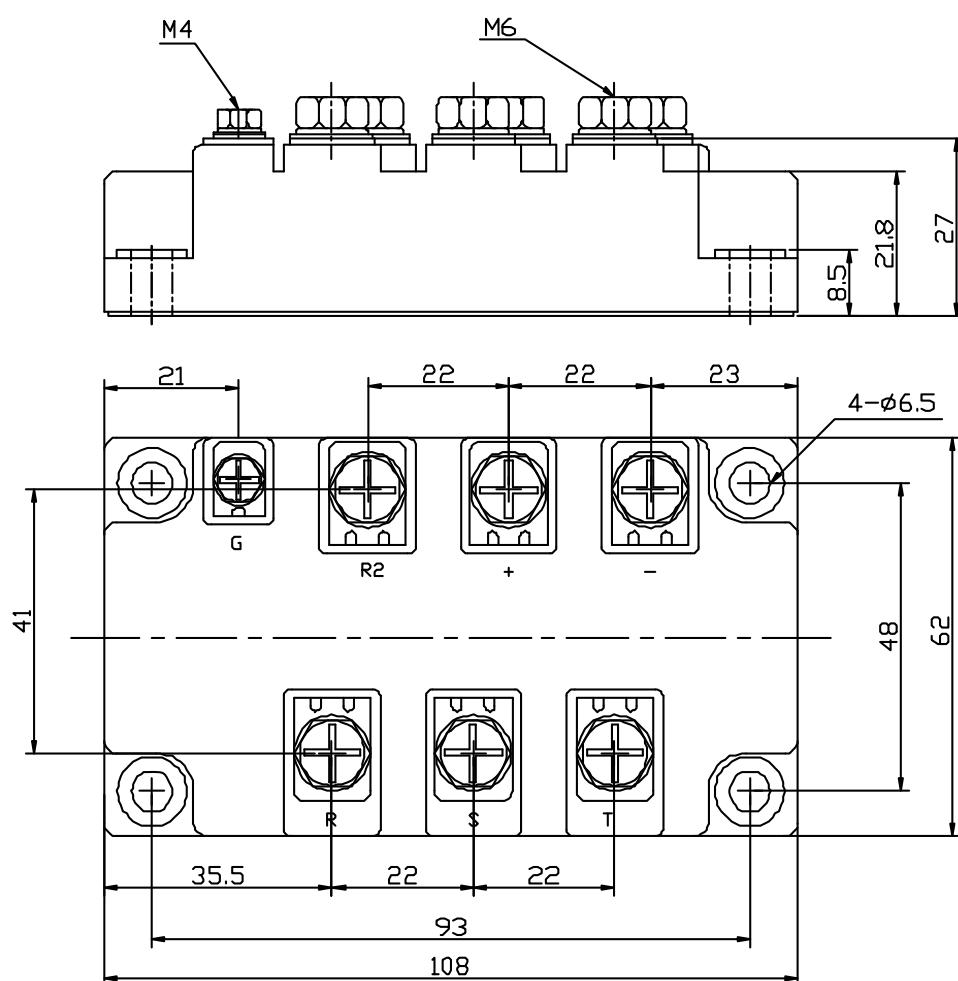


Fig10. Gate trigger Characteristics

## Package Outline Information



Dimensions in mm

